

IRFP22N50APbF

SMPS MOSFET

HEXFET® Power MOSFET

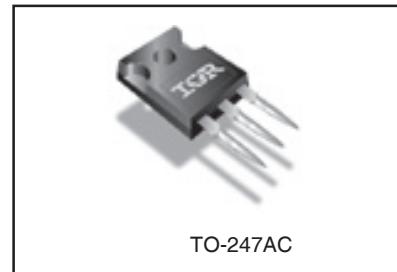
Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching
- Lead-Free

Benefits

- Low Gate Charge Qg results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dv/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current

V_{DSS}	R_{DS(on)} max	I_D
500V	0.23Ω	22A



Absolute Maximum Ratings

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	22	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	14	
I _{DM}	Pulsed Drain Current ①	88	
P _D @ T _C = 25°C	Power Dissipation	277	W
	Linear Derating Factor	2.2	W/°C
V _{GS}	Gate-to-Source Voltage	± 30	V
dv/dt	Peak Diode Recovery dv/dt ③	4.8	V/ns
T _J	Operating Junction and Storage Temperature Range	-55 to + 150	°C
T _{STG}	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Typical SMPS Topologies

- Full Bridge Converters
- Power Factor Correction Boost

Notes ① through ⑤ are on page 8
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Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	500	—	—	V	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	0.55	—	V°C	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$ ⑥
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.23	Ω	$V_{\text{GS}} = 10\text{V}, I_D = 13\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{\text{DS}} = 500\text{V}, V_{\text{GS}} = 0\text{V}$
				250		$V_{\text{DS}} = 400\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}} = 30\text{V}$
				-100		$V_{\text{GS}} = -30\text{V}$

Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	12	—	—	S	$V_{\text{DS}} = 50\text{V}, I_D = 13\text{A}$
Q_g	Total Gate Charge	—	—	120	nC	$I_D = 22\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	32	nC	$V_{\text{DS}} = 400\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	52	nC	$V_{\text{GS}} = 10\text{V}, \text{See Fig. 6 and 13}$ ④
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	26	—	ns	$V_{\text{DD}} = 250\text{V}$
t_r	Rise Time	—	94	—	ns	$I_D = 22\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	47	—	ns	$R_G = 4.3\Omega$
t_f	Fall Time	—	47	—	ns	$R_D = 11\Omega, \text{See Fig. 10}$ ④
C_{iss}	Input Capacitance	—	3450	—	pF	$V_{\text{GS}} = 0\text{V}$
C_{oss}	Output Capacitance	—	513	—	pF	$V_{\text{DS}} = 25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	27	—	pF	$f = 1.0\text{MHz}, \text{See Fig. 5}$
C_{oss}	Output Capacitance	—	4935	—	pF	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 1.0\text{V}, f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	137	—	pF	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 400\text{V}, f = 1.0\text{MHz}$
$C_{\text{oss eff.}}$	Effective Output Capacitance	—	264	—	pF	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V to } 400\text{V}$ ⑤

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	1180	mJ
I_{AR}	Avalanche Current①	—	22	A
E_{AR}	Repetitive Avalanche Energy①	—	28	mJ

Thermal Resistance

	Parameter	Typ.	Max.	Units
R_{0JC}	Junction-to-Case	—	0.45	°C/W
R_{0CS}	Case-to-Sink, Flat, Greased Surface	0.24	—	°C/W
R_{0JA}	Junction-to-Ambient	—	40	°C/W

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	22	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	88	A	
V_{SD}	Diode Forward Voltage	—	—	1.5	V	$T_J = 25^\circ\text{C}, I_S = 22\text{A}, V_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	570	850	ns	$T_J = 25^\circ\text{C}, I_F = 22\text{A}$
Q_{rr}	Reverse Recovery Charge	—	6.1	9.2	μC	$dI/dt = 100\text{A}/\mu\text{s}$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

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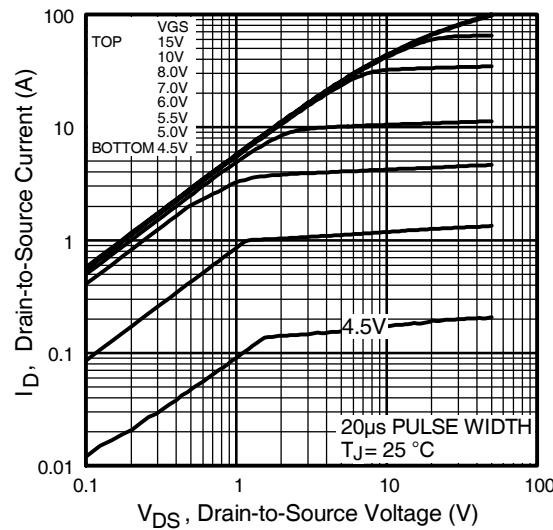


Fig 1. Typical Output Characteristics

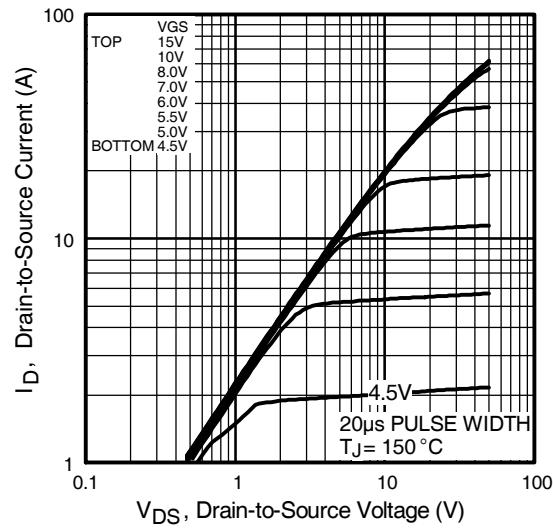


Fig 2. Typical Output Characteristics

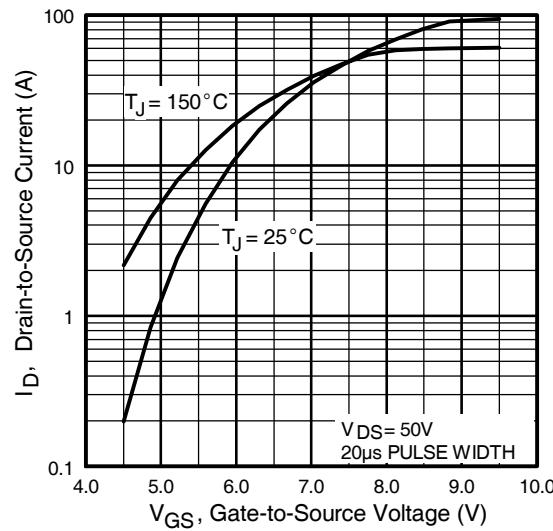


Fig 3. Typical Transfer Characteristics

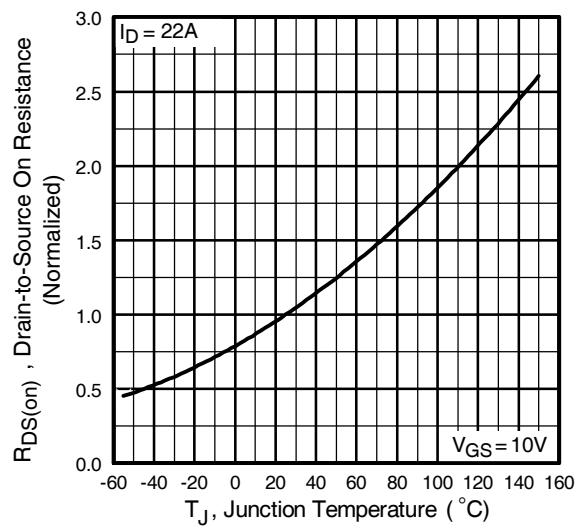


Fig 4. Normalized On-Resistance
Vs. Temperature

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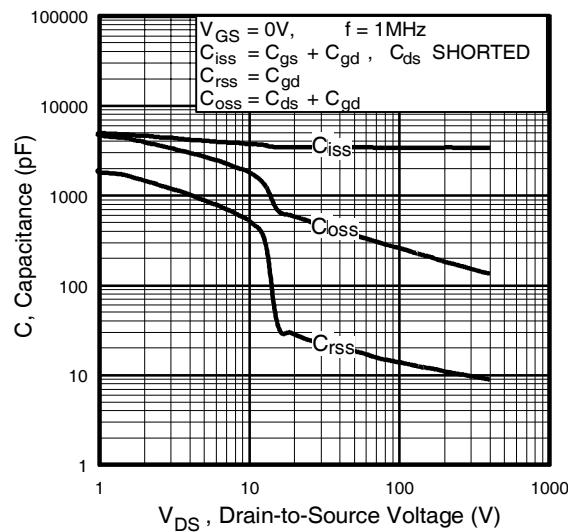


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

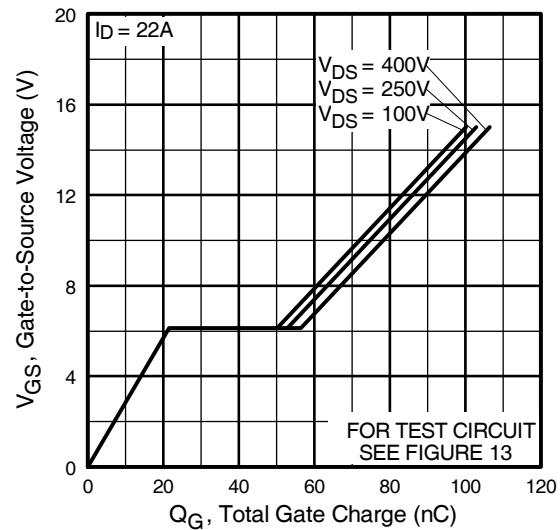


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

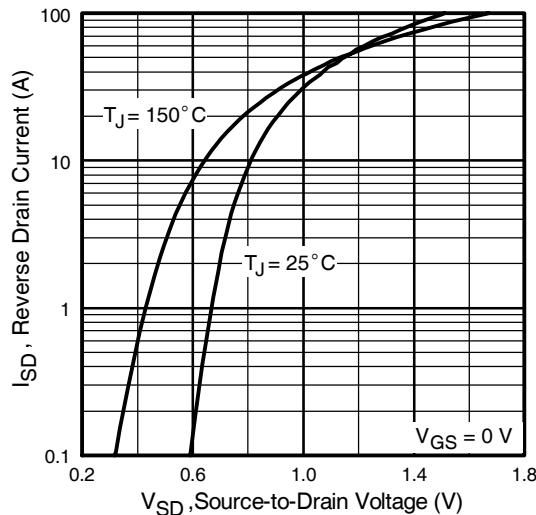


Fig 7. Typical Source-Drain Diode
Forward Voltage

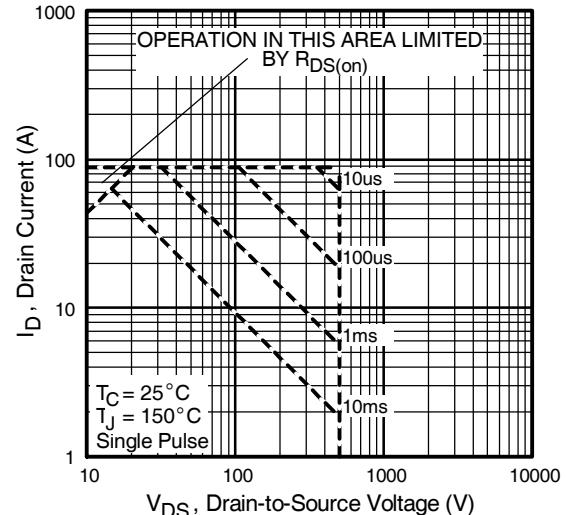


Fig 8. Maximum Safe Operating Area

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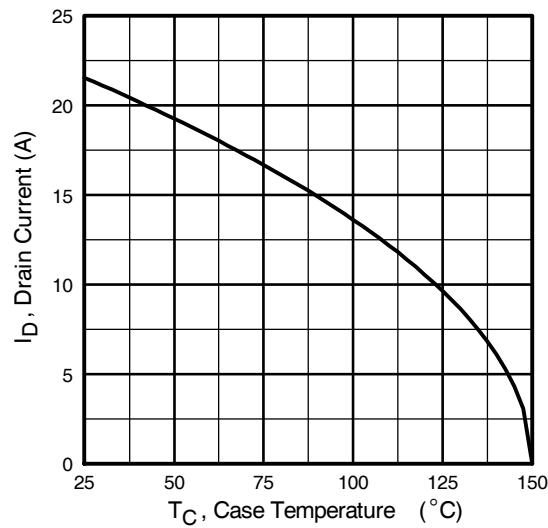


Fig 9. Maximum Drain Current Vs.
Case Temperature

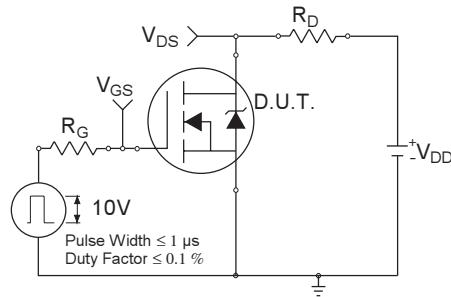


Fig 10a. Switching Time Test Circuit

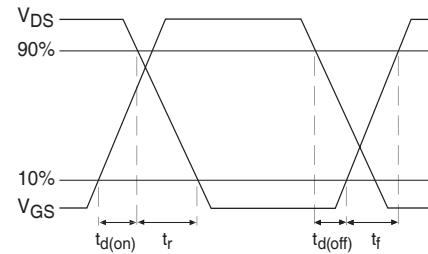


Fig 10b. Switching Time Waveforms

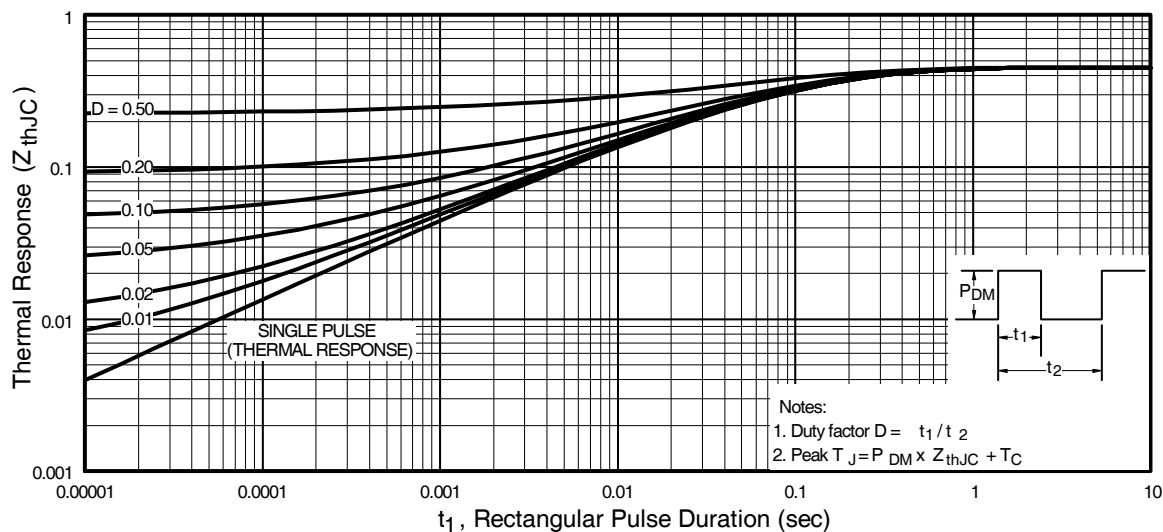


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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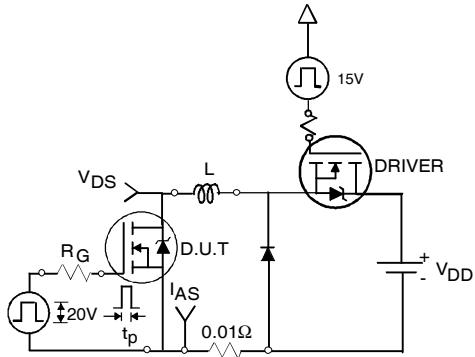


Fig 12a. Unclamped Inductive Test Circuit

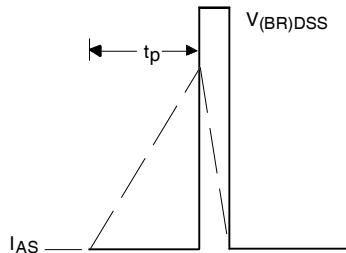


Fig 12b. Unclamped Inductive Waveforms

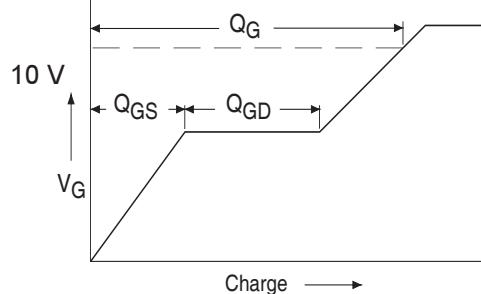


Fig 13a. Basic Gate Charge Waveform

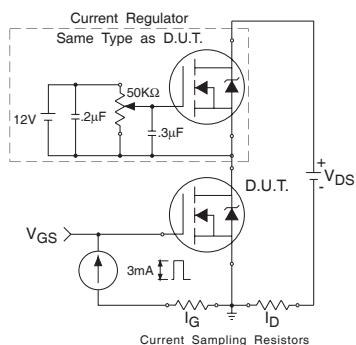


Fig 13b. Gate Charge Test Circuit

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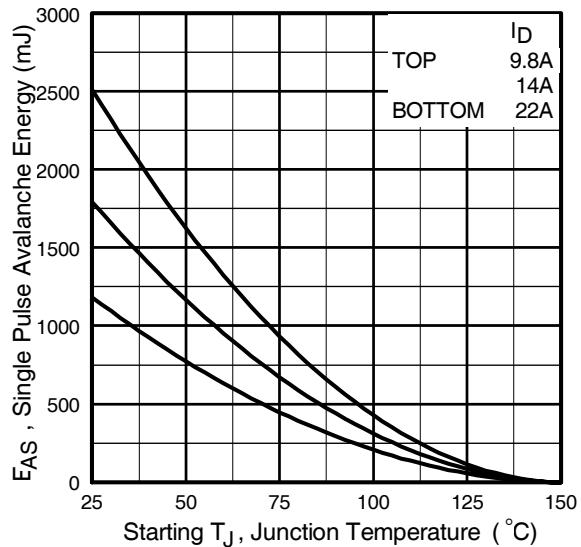


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

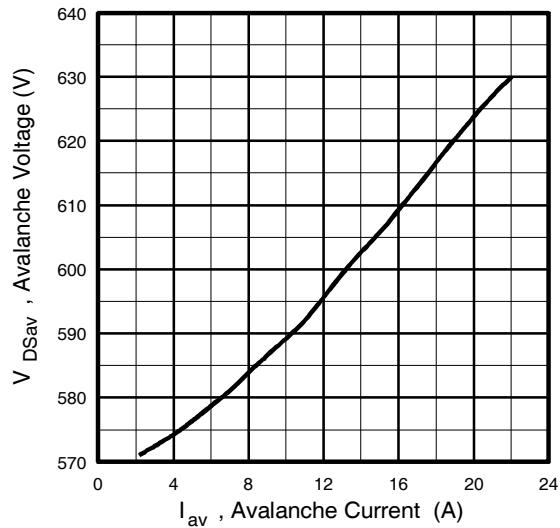
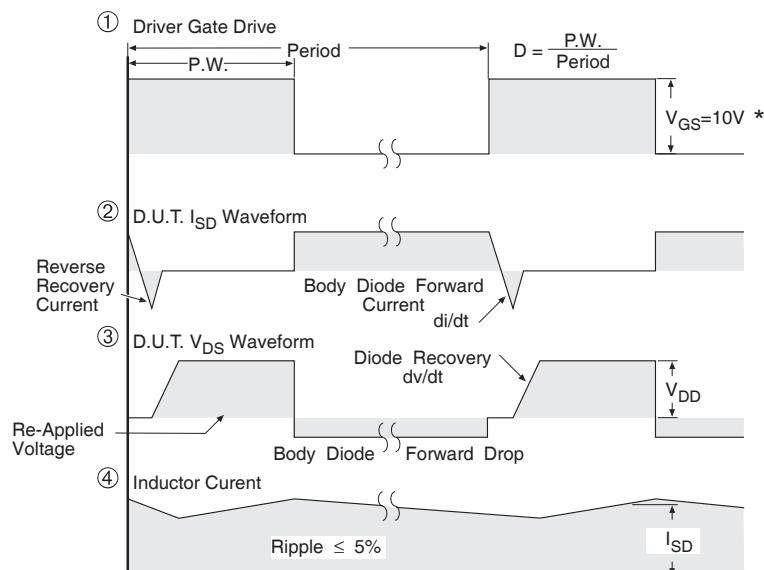
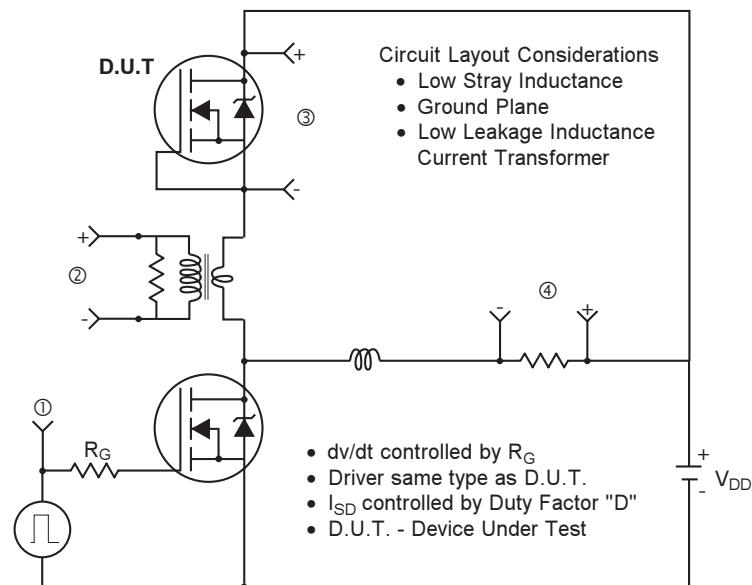


Fig 12d. Typical Drain-to-Source Voltage Vs. Avalanche Current

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Peak Diode Recovery dv/dt Test Circuit



* $V_{GS} = 5V$ for Logic Level Devices

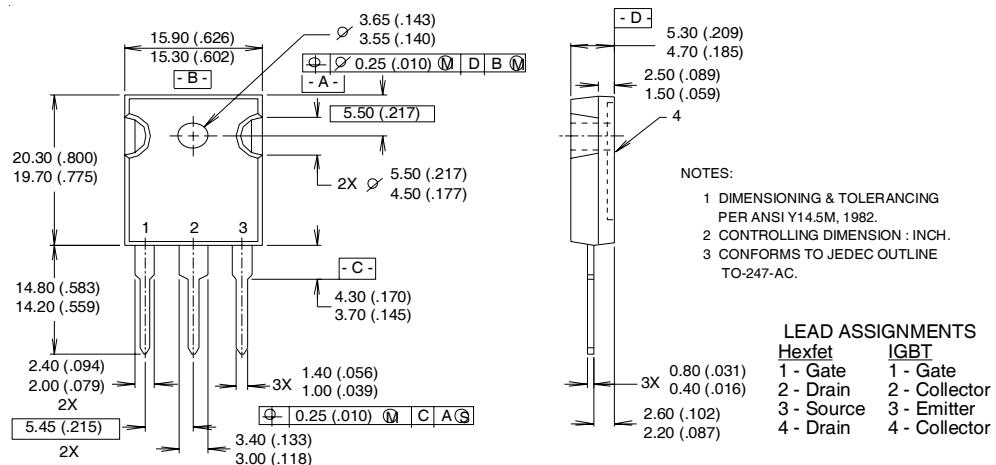
Fig 14. For N-Channel HEXFET® Power MOSFETs

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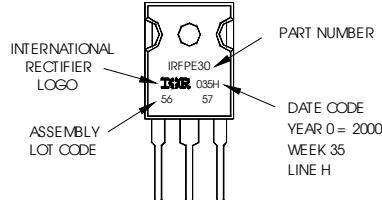
TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30 WITH ASSEMBLY LOT CODE 5657 ASSEMBLED ON WW35, 2000 IN THE ASSEMBLY LINE 'H'
Note: "P" in assembly line position indicates "Lead-Free"



Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting $T_J = 25^\circ\text{C}$, $L = 4.87\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = 22\text{A}$. (See Figure 12a)
- ③ $I_{SD} \leq 22\text{A}$, $\text{di}/\text{dt} \leq 190\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})DSS}$, $T_J \leq 150^\circ\text{C}$
- ④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑤ C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}

Data and specifications subject to change without notice.

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